


REMARKS

Claims 1-39 are pending. By this Preliminary Amendment, claims 12, 19, 21, 22, 31 and 38 are amended to eliminate multiple dependencies. Prompt and favorable examination on the merits is respectfully solicited.

The attached Appendix includes marked-up copies of each rewritten claim (37 C.F.R. 1.121(c)(ii)).

Respectfully submitted,



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Attachment:
Appendix

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<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>

APPENDIX

Changes to Claims:

The following are marked-up versions of the amended claims:

12. (Amended) The interconnect substrate as defined in ~~any of claims 1 to 11,~~
claim 1, wherein the first and second substrates are adhered by an anisotropic conductive film
including conductive particles.

19. (Amended) The electronic component as defined in ~~any of claims 15 to 18,~~
claim 15, wherein: an anisotropic conductive film including conductive particles is provided
on the surface of the second substrate on which the second interconnect pattern is formed; and
the anisotropic conductive film adheres the first substrate to the second substrate, while also
electrically connecting the second interconnect pattern to the electronic chip.

21. (Amended) A circuit board on which is mounted the electronic component as
defined in ~~any of claims 14 to 18,~~ claim 14.

22. (Amended) An electronic instrument equipped with the electronic component
as defined in ~~any of claims 14 to 18,~~ claim 14.

31. (Amended) The method of manufacture of an interconnect substrate as
defined in ~~any of claims 23 to 30,~~ claim 23, wherein: positioning holes are formed in the first
and second substrates; and before the disposition step, a step is included in which a jig is put
into the positioning holes and the first and second substrates are positioned.

38. (Amended) The method of manufacture of an electronic component as defined
in ~~any of claims 32 to 37,~~ claim 32, wherein the disposition step is carried out after the first
mounting step.